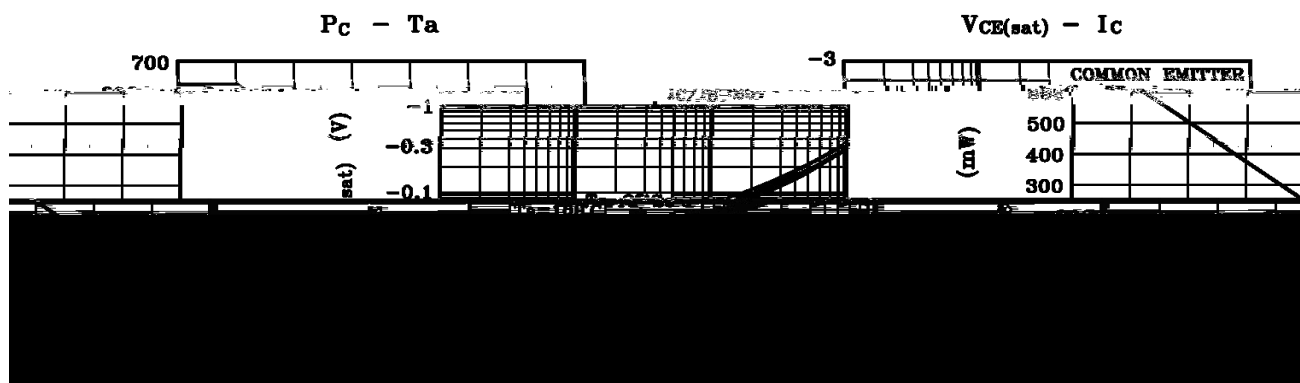
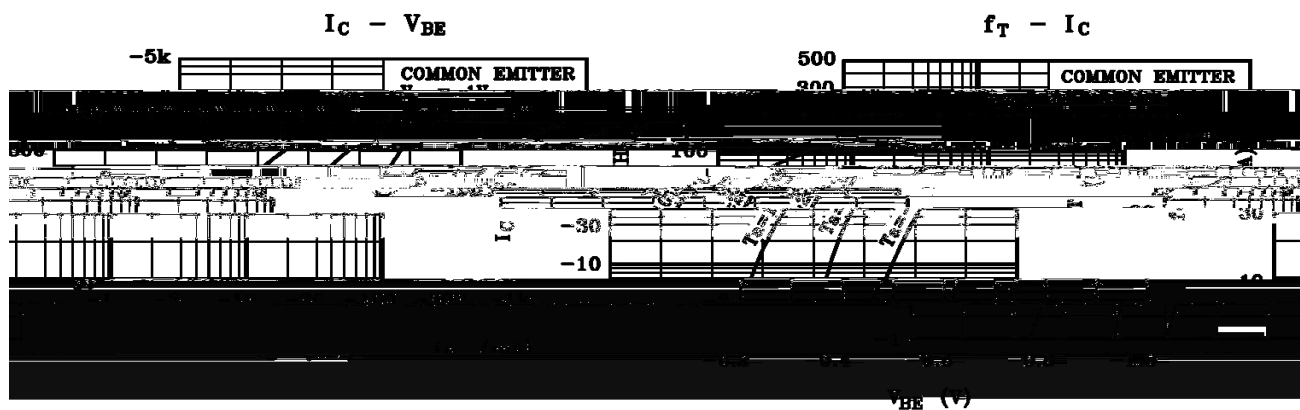


/ Absolute Maximum Ratings(Ta=25 °C)

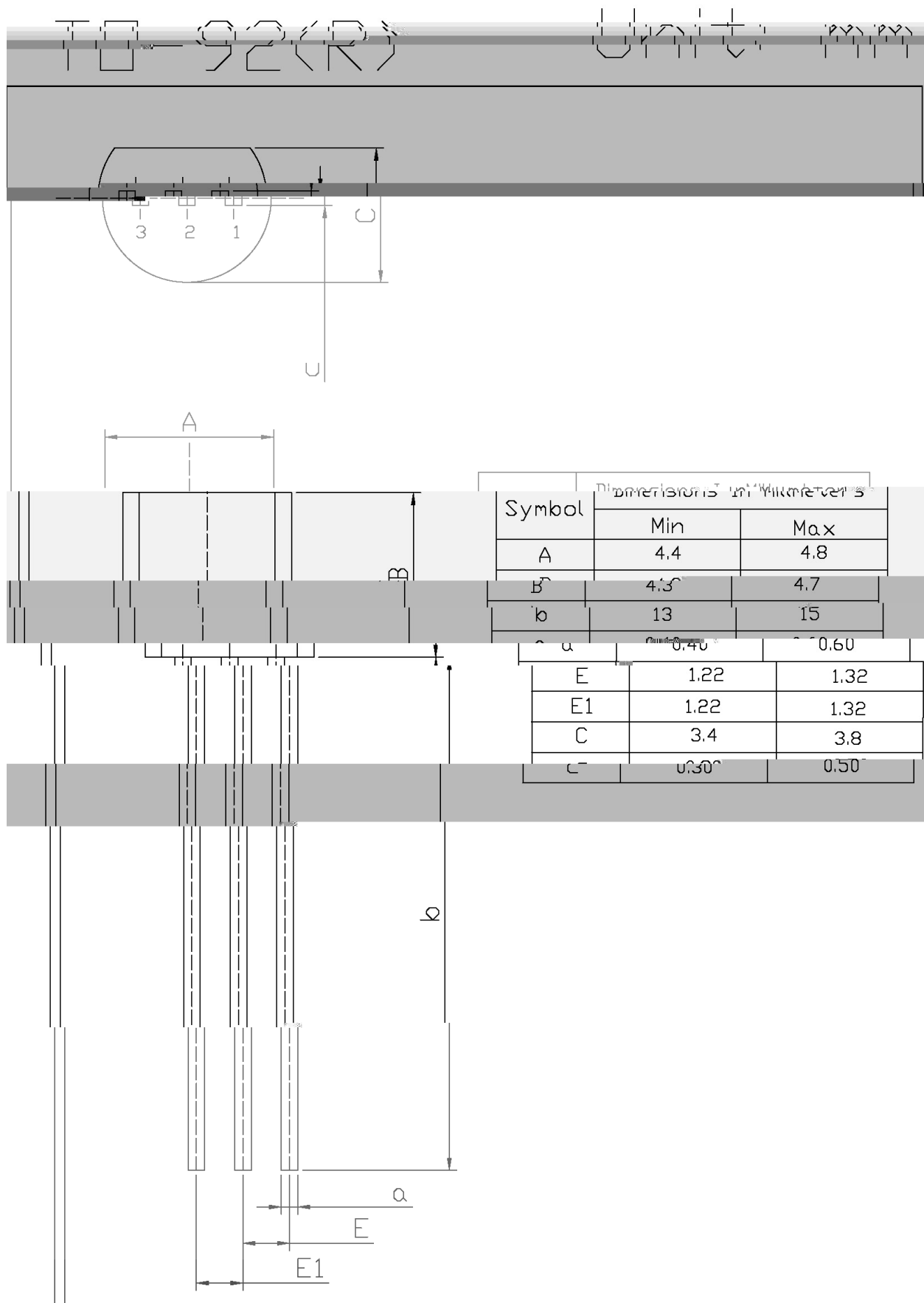
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-30	V
Collector to Emitter Voltage	V_{CEO}	-25	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-800	mA
Emitter Current - Continuous	I_E	800	mA
Collector Power Dissipation	P_C	625	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 ~ 150	

/ Electrical Characteristics(Ta=25 °C)

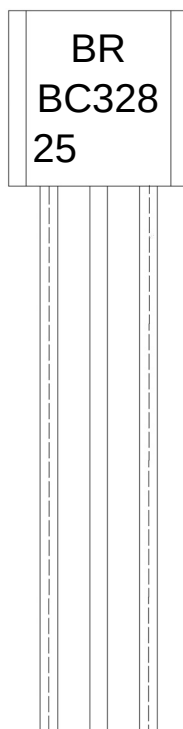
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-25V$ $I_E=0$			-0.1	A
DC Current Gain	h_{FE}	$V_{CE}=-1.0V$ $I_C=-100mA$	100		600	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-500mA$ $I_B=-50mA$			-0.7	V
Base to Emitter On Voltage	$V_{BE(ON)}$	$V_{CE}=-1.0V$ $I_C=-300mA$			-1.2	V
Transition Frequency	f_T	$V_{CE}=-5.0V$ $I_C=-10mA$ $f=100MHz$		100		MHz
Collector output capacitance	C_{ob}	$V_{CB}=-10V$ $f=1.0MHz$		16		pF



/ Package Dimensions



/ Marking Instructions



Б " X

EU X ㄣ 3 1 7

EF65; X ㄣ F β 3 N

58: ㄣ k_{1H}' 6 7

---- X ㄣ 1 F 7 N 7 1 4 1 F 7 N ψ ρ

Note:

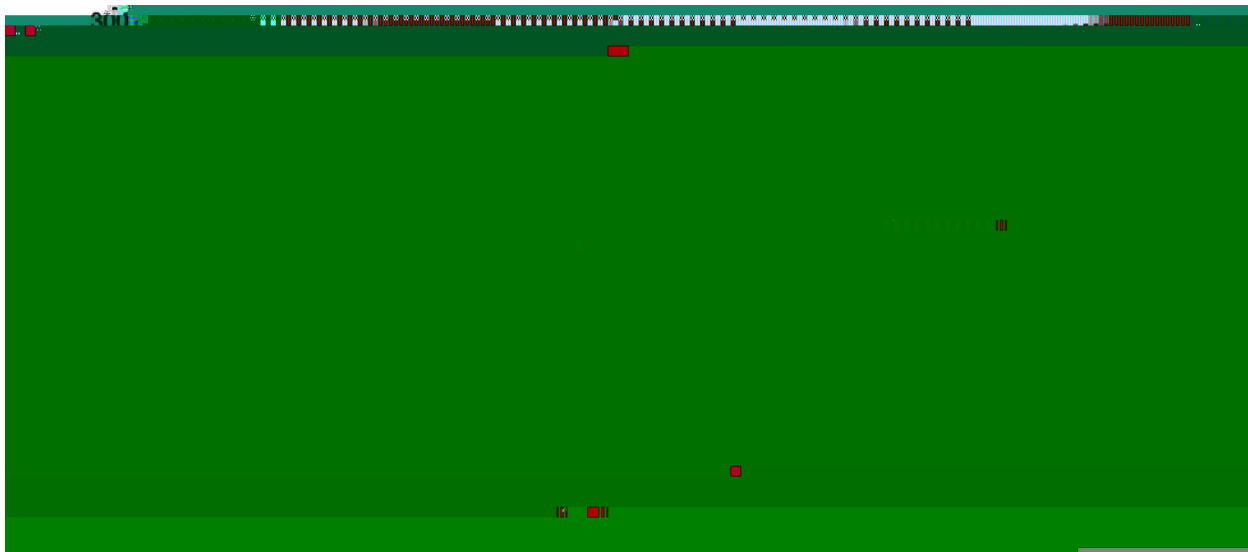
BR: Company Code.

BC328: Product Type.

25: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



б " X

1. 1. Preheating: 25~150 °C, Time: 60~90sec;
2. 2. Peak Temp.: 255 °C, Duration: 5 °C 0.5sec;
3. 3. Cooling Speed: 2~10 °C /sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 255 °C, Duration: 5 °C 0.5sec.
3. Cooling Speed: 2~10 °C /sec.

/ Resistance to Soldering Heat Test Conditions

□ °C 270 ± 5 °C °C 10 ± 1 sec. Temp.: 270 ± 5 Time: 10 ± 1 sec

/ Packaging SPEC.

°C °C / BULK

Package Type	Units					Dimension		(unit mm3)

°C °C / AMMO

Package Type	Units					Dimension		(unit mm3)

/ Notices